AMENDMENTS TO THE SPECIFICATION

Please replace previously amended paragraph **[0002]** with the following amended paragraph:

[0002] The following co-pending and commonly-assigned U.S. Patent Applications, filed on even date herewith, are also incorporated herein by reference in their entirety:

1. U.S. Patent Application Serial No. 10/731,869, entitled "MODULAR IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed on December 9, 2003;
2. U.S. Patent Application Serial No. 10/731,868, entitled "IMPLANTATION OF LOW-PROFILE IMPLANTABLE MEDICAL DEVICE," to Ruchika Singhal et al., and filed on December 9, 2003;
3. U.S. Patent Application Serial No. 10/731,699, entitled "COUPLING MODULE OF A MODULAR IMPLANTABLE MEDICAL DEVICE," to Darren A. Janzig et al., and filed on December 9, 2003;
4. U.S. Patent Application Serial No. 10/730, 873, entitled "OVERMOLD FOR A MODULAR IMPLANTABLE MEDICAL DEVICE," to Ruchika Singhal et al., and filed on December 9, 2003, which issued as U.S. Patent No. 7,242,982 on July 10, 2007;
5. U.S. Patent Application Serial No. 10/731,881, entitled "REDUCING RELATIVE INTERMODULE MOTION IN A MODULAR IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed on December 9, 2003, which issued as U.S. Patent No. 7,392,089 on June 24, 2008;
6. U.S. Patent Application Serial No. 10/730,878, entitled "LEAD CONNECTION MODULE OF A MODULAR IMPLANTABLE MEDICAL DEVICE," to Ruchika Singhal et al., and filed on December 9, 2003;
7. U.S. Patent Application Serial No. 10/730,877, entitled "LOW-PROFILE IMPLANTABLE MEDICAL DEVICE," to Darren A. Janzig et al., and filed on December 9, 2003; and

8. U.S. Patent Application Serial No. 10/731,638, entitled "MODULAR IMPLANTABLE MEDICAL DEVICE," to Carl D. Wahlstrand et al., and filed on December 9, 2003, which issued as U.S. Patent No. 7,212,864 on May 1, 2007.

Please replace paragraph **[0051]** of the originally-filed application with the following amended paragraph:

[0051] Overmold 48 can be shaped to contour to cranium 12, e.g., may be concave along at least one axis, and may be contoured at its edges to prevent skin erosion on the scalp of patient 14. The flexibility and shape, e.g., concavity, of overmold 48 may improve the comfort and cosmetic appearance of modular IMD 10 under the scalp. Further details regarding the overmold and techniques for restricting intermodular motion in a modular IMD 10 may be found in a commonly-assigned U.S. Patent Application Serial No. 10/730,873, entitled "OVERMOLD FOR A MODULAR IMPLANTABLE MEDICAL DEVICE," now issued as U.S. Patent No. 7,242,982, and a commonly-assigned U.S. Patent Application Serial No. 10/731,881, entitled "REDUCING RELATIVE INTERMODULE MOTION IN A MODULAR IMPLANTABLE MEDICAL DEVICE," now issued as U.S. Patent No. 7,392,089.[["]]